



Application No.: HENK-0022
Application No.: 09/807,948
Office Action Dated: July 17, 2003

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Paul Ranft, et al

Confirmation No.: **9265**

Application No.: **09/807,948**

Group Art Unit: **1733**

Filing Date: **November 27, 2001**

Examiner: **John L. Goff II**

For: **Hot-Melt Adhesive Component Layers For Smart Cards**

EXPRESS MAIL LABEL NO: **EL 969190710 US**
DATE OF DEPOSIT: **November 12, 2003**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

REPLY PURSUANT TO 37 CFR § 1.111

In response to the Official Action dated **July 17, 2003**, reconsideration is respectfully requested in view of the amendments and/or remarks as indicated below:

- ☐ **Amendments to the Specification** begin on page _____ of this paper.
- ☒ **Amendments to the Claims** are reflected in the listing of the claims which begins on page 2 of this paper.
- ☐ **Amendments to the Drawings** begin on page _____ of this paper and include an attached replacement sheet.
- ☒ **Remarks/Arguments** begin on page 4 of this paper.

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